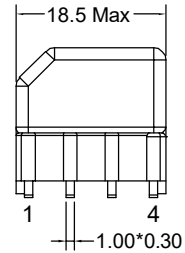
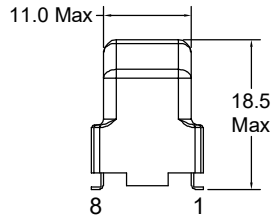




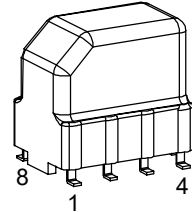
Outline Dimensions(Unit:mm)



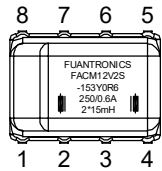
Orthographic view



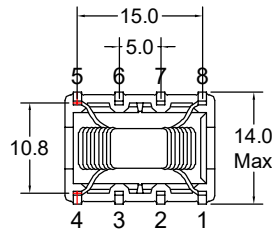
Side view



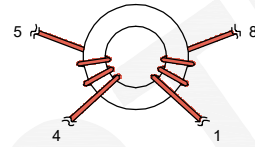
Stereogram



Top view

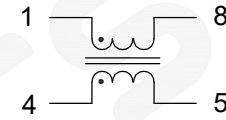


Bottom view

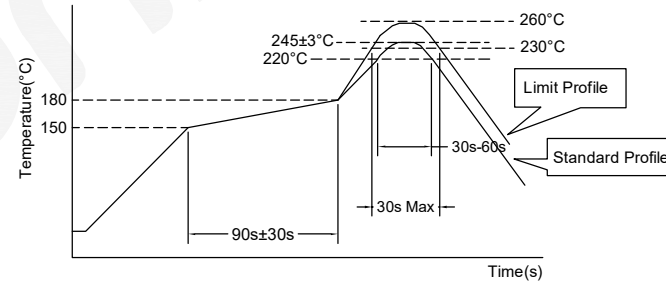


Winding Construction

Electronical Schematic



Recommended Soldering Temperature Graph.



	Standard Profile	Standard Profile
Pre-heating	150~180°C, 90s±30s	
Heating	above 220°C, 30s-60s	above 240°C, 30s Max
Peak temperature	245°C±3°C	260°C, 10s
Cycle of reflow	2 times	

Electrical Characteristics(at 25°C)

Inductance : L1-8=4-5= 15mH +50%/-30%,at 10KHZ,0.1V.

Leakage Inductance: L1-8&4-5= 170uH Typ.

Rated current: 0.6Amps.

D.C.Resistance : 1-8= 0.700 ohms Typ.

4-5= 0.700 ohms Typ.

Turns Ratio : Coil:Coil= 1:1±2%,at 20KHZ,1V.

Hipot : Coil-Coil : 1500VAC/5mA/2Second.

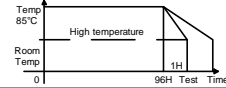
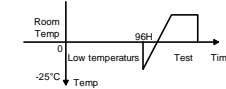
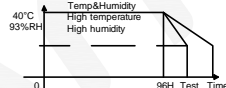
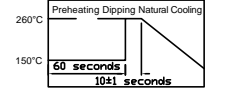
List of UL Certificate:


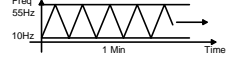
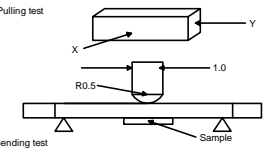
Part Name	Mat'l Description	Supplier	UL Number
Case	EB16-001S/PA66(orange)	Zhejiang Juner New Materials Co Ltd	E204321
Copper wire	2UEW-F/155C	Elektrisola Hangzhou Co Ltd	E258243
Core	Ferrite core(orange)	Su Zhou Tian Ming Magnetic	N/A
Epoxy	808A-R-B(red soft glue)	Dong Guan Shi Pai Hua Chuang Material Fty	E304477
Spacer	0.50mm/FR-4	Kingboard Laminates Holdings Ltd	E123995

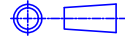
				Tianchang Fuan Electronic Co Ltd www.fuantronics.net TEL: +86-550-7814888 FAX: +86-550-7831133	 Tolerances unless otherwise specified: (.X)±0.50 (.XX)±0.25 Unit of measurement: mm	Make: Qiumei.Liu Checked: Beson. zhan Approved: Anson. zhan	<b>DRAWING TITLE</b> CURRENT-COMPENSATED RING CORE DOUBLE CHOKES Material Number: A31CM012S950	Customer P/N: Document/Rev: 00 Specification Sheet: 1 of 1 Date of Recognition: Nov./18/2023
REV	DESCRIPTION	APPD	DATE					

## Reliability Testing:



Ltem	Specified value	Test methods
High temperature Storage test Reference documents: MIL-STD-202G Method 108A	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ .	Temperature: $85 \pm 2^\circ\text{C}$ Time: $96 \pm 2$ hours.  Tested not less than 1 hour, not more than 2 hours at room temperature. 
Low temperature Storage test. Referencedocuments: IEC 68-2-1A 6.1 6.2	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ .	Temperature: $25 \pm 2^\circ\text{C}$ Time: $96 \pm 2$ hours.  Tested not less than 1 hour, not more than 2 hours at room temperature. 
Humidity test Reference Documents: MIL-STD-202G Method 103B	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ .	1.Dry oven at a temperature of $40^\circ \pm 5^\circ\text{C}$ for 24 hours. 2.Measurements At the end of this period 3.Exposure:Temperature: $40 \pm 2^\circ\text{C}$ , Humidity: $93 \pm 3\% \text{RH}$ Time: $96 \pm 2$ hours. 4.Tested while the specimens are still in the chamber. 5.Tested not less than 1 hour, nor more than 2 hours at room temperature. 
Heat endurance of Reflow soldering	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ .	Preheat: $150^\circ\text{C}$ , 60 second. Solder:Sn/Ag/Cu. Solder:Temperature: $260 \pm 5^\circ\text{C}$ . Flux:Rosin flux. Reflow peak time 10 second at $260^\circ\text{C}$ 

Ltem	Specified value	Test methods
Thermal shock test Reference documents: MIL-STD-202G Method 107G	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ . For T:weiges $\leq 28\text{g}$ : 15 Min 28g $\geq$ weights $\leq 136\text{g}$ : 30 Min	First- $40^\circ\text{C}$ for T time,next+ $125^\circ\text{C}$ Time as 1 cycle. Go through 20 cycles. 
Solderability test Reference documents: MIL-STD-202G Method 208H IPC J-STD-002B	Terminals area must have 95% Min. Solder coverage.	Dip pads in flux then dip in solder pot at $245 \pm 5^\circ\text{C}$ for 5 second. Soler:Sn(93.5)Ag(3.5). Flux:Rosin flux.
Vibration test Reference documents: MIL-STD-202G Method 201A	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ .	Apply frequency 10–55Hz. 0.75mm amplitude in each of perpendicular direction for 2 hours.(total 6 hours). 
Drop test Reference documents: MIL-STD-202G Method 203G	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ . For T:weiges $\leq 28\text{g}$ : 15 Min 28g $\geq$ weights $\leq 136\text{g}$ : 30 Min	Packaged & Drop down from 1m with $981\text{m/s}^2$ (100G) attitude in 1 angle 1 ridges & 2 surfaces orientations.
Terminal strength push test Reference documents: JIS C 5321:1997	Pulling test: DEFINE:A:sectional area of terminal $A \leq 8(\text{Sq M})$ Force $\geq 5\text{N}$ time:30sec $8(\text{Sq M}) < A \leq 20(\text{Sq M})$ Force $\geq 10\text{N}$ time:10sec $20(\text{Sq M}) < A$ force $\geq 20\text{N}$ time:10sec Bending test: Soldering the products on PCB,after the pulling testand bending test, terminal should not pull off	Bend the testing PCB at middle point, the deflection shall be 2mm 

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Ltem	Specified value	Test methods
Resistance to solvent test Reference documents: IEC 68-2-45:1993	No case deformation or change in appearance, or obliteration of marking	To dip parts into IPA solvent for 5±0.5Min, then drying them at room temp for 5 Min, at last, to brushing making 10 times.
Electronic characteristic test of major products	Refer to catalogue of specific products	Refer to catalogue of specific products
Overload test Reference documents:	1. During the test no smoke, no peculiar, smell, no fire	Apply twice as rated current for 5 minutes.

Recommended solderability temperature profile:



Use rosin-based flux  
 Don't use high acidic flux with halide content exceeding 0.2(wt)% (chlorine conversion value).  
 Use lead-free solder, use Sn-3.0Ag-0.5Cu solder  
 Standard thickness of solder paste: 0.12-0.15mm

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